ES3AC THRU ES3JC

Reverse Voltage - 50 to 600 Volts Forward Current - 3.0 Ampere

SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

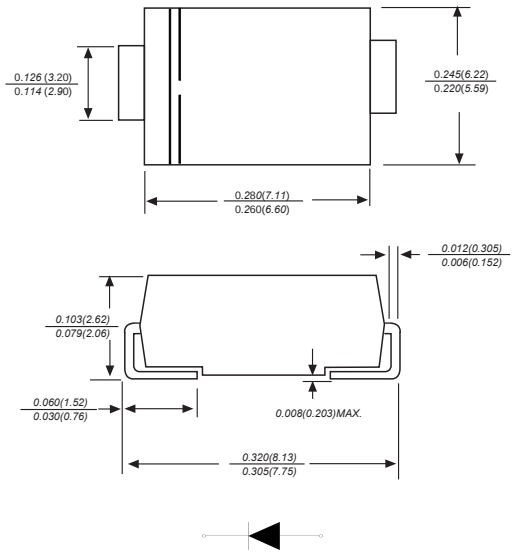
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief,ideal for automated
- placement High forward surge current capability
- High temperature soldering guaranteed:
- 250°C/10 seconds at terminals

  Glass passivated chip junction

RoHS COMPLIANT

DO-214AB/SMC



Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC DO-214AB/SMC Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0077ounce, 0.22grams

Maximum Ratings And Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

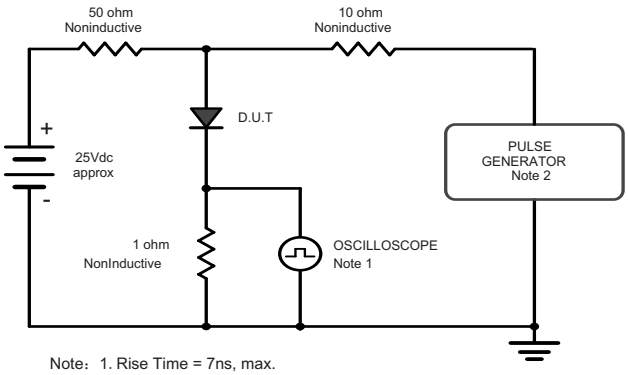
Parameter / Marking Code	SYMBOLS	MDD ES3AC	MDD ES3BC	MDD ES3CC	MDD ES3DC	MDD ES3EC	MDD ES3GC	MDD ES3JC	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at TL=125℃	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I_{FSM}	90							A
Maximum instantaneous forward voltage at 3.0A	V_F	1				1.25		1.68	V
Maximum DC reverse current at rated DCblocking voltage TA=25℃ / TA=125℃	I_R	5.0 / 100							μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	35							ns
Typical junction capacitance (NOTE 2)	C_J	40							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ / $R_{\theta JC}$	40 / 16							℃/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150							℃

Note:1.Reverse recovery condition I_F=0.5A,I_R=1.0A,Irr=0.25A
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3.P.C.B. mounted with 2.0"x2.0"(5.0x5.0cm) copper pad areas

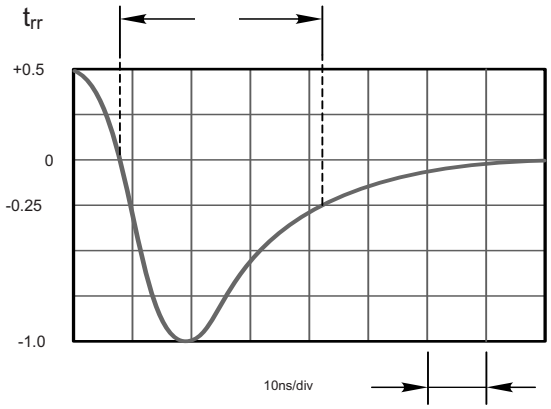
DN:T21315A1

Ratings And Characteristic Curves

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note：1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

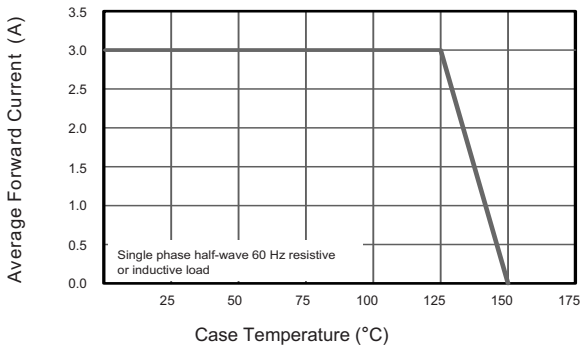


Fig.3 Typical Reverse Characteristics

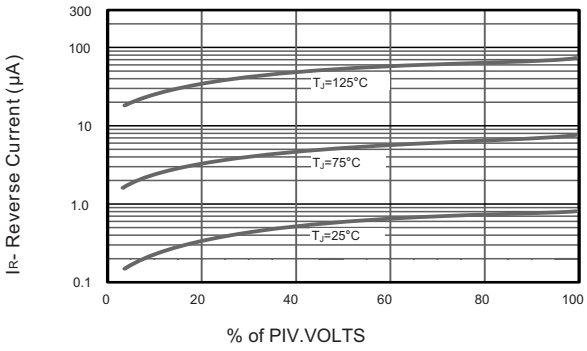


Fig.4 Typical Forward Characteristics

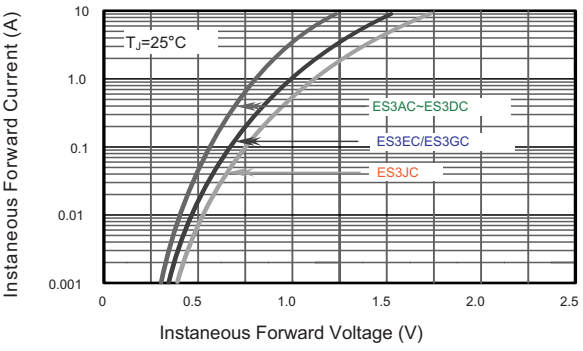


Fig.5 Typical Junction Capacitance

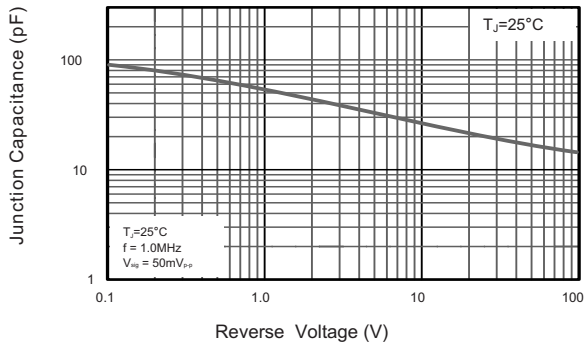
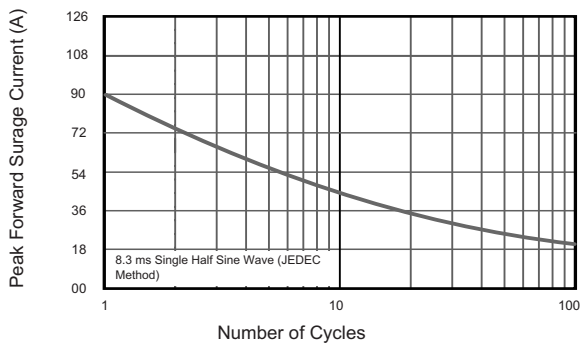
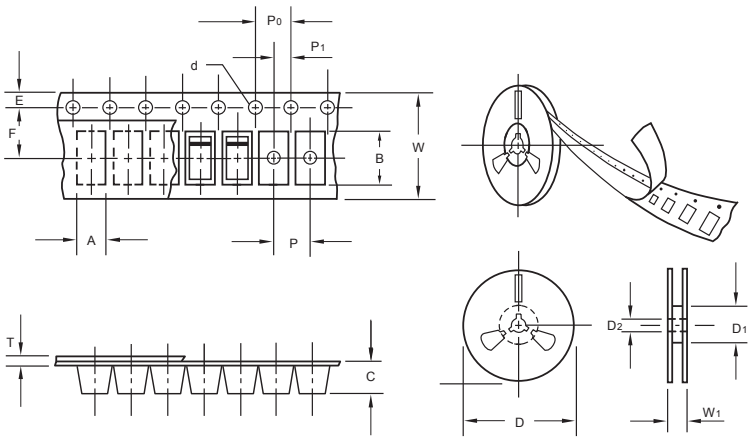


Fig.6 Maximum Non-Repetitive Peak Forward Surage Current



The curve above is for reference only.

Packing information



unit:mm

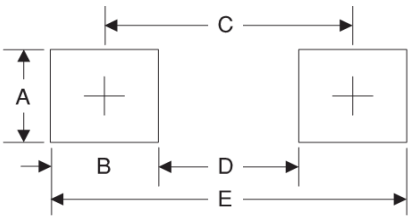
Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D_1	min	50.00
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W_1	1.0	16.50

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	190*190*41	330	365*365*340	42000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472